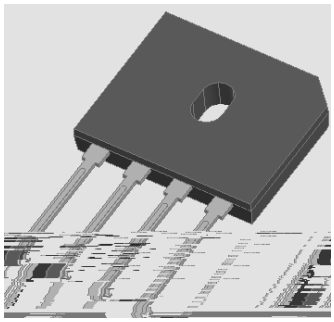
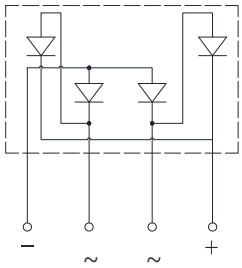
Super Fast Recovery Bridge Rectifiers





Features

- UL recognition, file #E230084
- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for monitor, TV, printer, power supply, switching mode power supply, adapter, audio equipment, and home appliances applications.

Mechanical Data

- **Package**: GBU
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■Maximum Ratings (T_a=25 Unless otherwise specified

PARAMETER		SYMBOL	UNIT	EGBU2006
Device marking code				EGBU2006
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	V	600
Maximum RMS Voltage		V_{RMS}	V	420
Maximum DC blocking Voltage		V_{DC}	V	600
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =100	I_O	A	20.0
	Without heatsink Ta =25			3.0
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25		I_{FSM}	A	180
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25				360
Current squared time @1ms≤t≤8.3ms Tj=25 , Rating of per diode		I^2t	A^2S	134
Storage temperature		T_{stg}		-55 ~ +150
Junction temperature		T_j		-55 ~ +150
Dielectric strength @ Terminals to case, AC 1 minute		Vdis	KV	2.5
Mounting torque @Recommend torque 5kg cm		Tor	kg cm	8

■Electrical Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	EGBU2006
Maximum reverse recovery time	T_{RR}	ns	I_F=0.5A,I_R=1.0A, I_{RR}=0.25A	35
Maximum instantaneous forward voltage drop per diode	V_F	V	I_{FM}=10.0A	2.0
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	T_j=25	5
			T_j=125	100
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	80

■Thermal Characteristics T_a=25 Unless otherwise specified

PARAMETER		SYMBOL	UNIT	EGBU2006
Thermal Resistance	Between junction and ambient, Without heatsink	$R_{\theta J-A}$	/W	16
	Between junction and case, With heatsink	$R_{\theta J-C}$		2.3

Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs

FIG3: Typical Forward Voltage

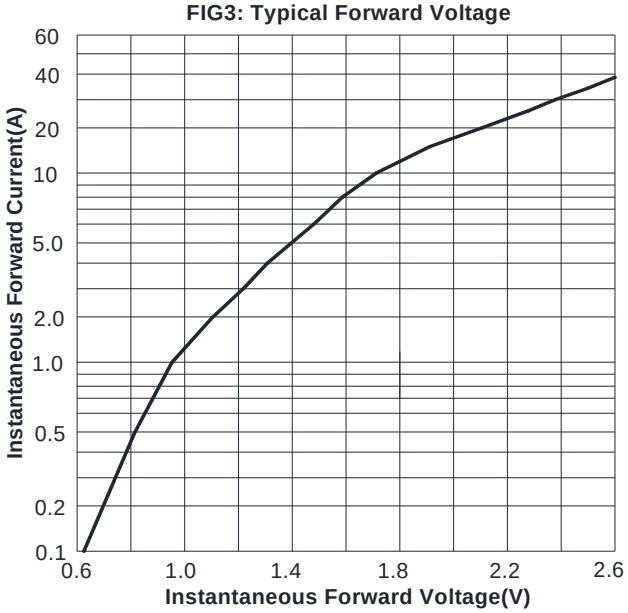


FIG4:Typical Reverse Characteristics

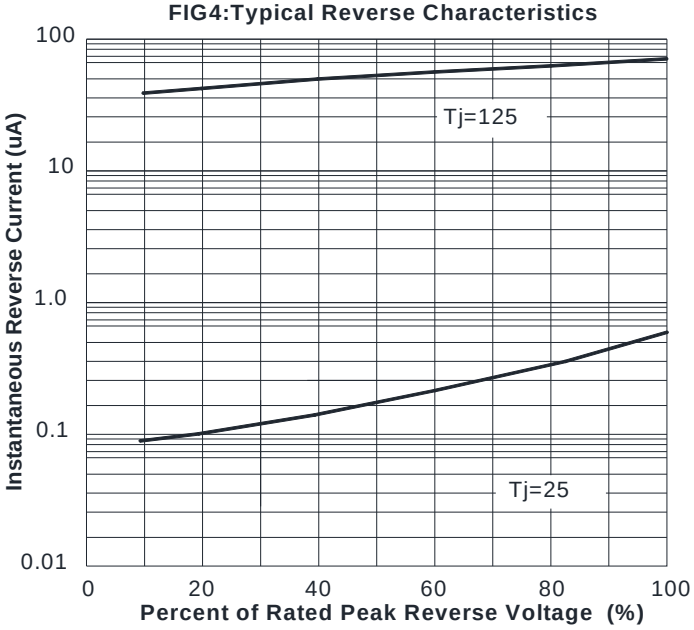
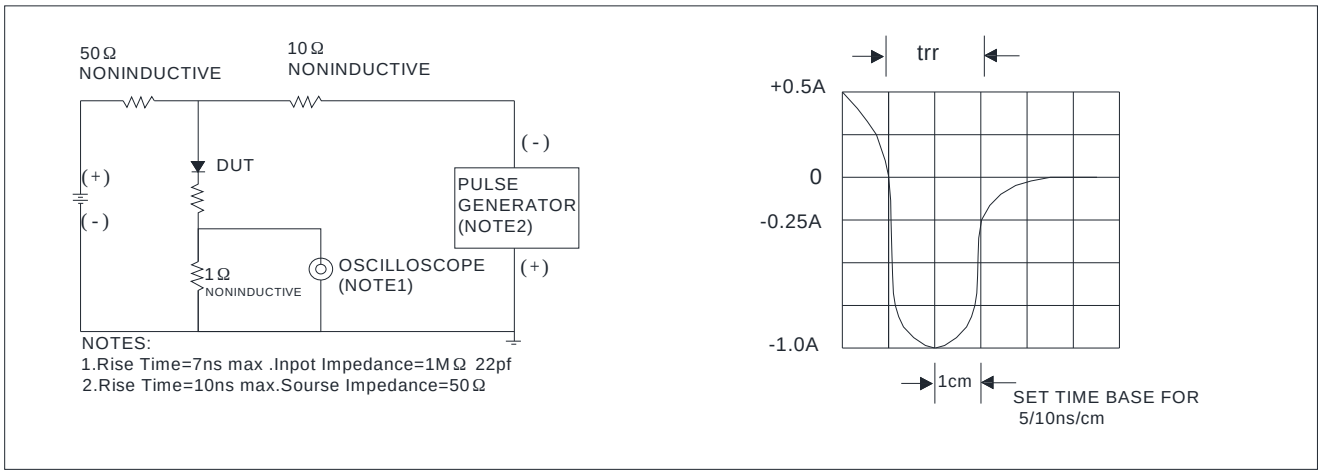
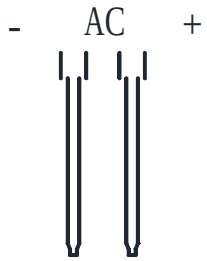


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



■ Outline Dimensions

GBU		
Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	17.50	18.00
D	3.30	3.90
E	7.10	7.50
F	5.50	5.90
G	1.91	2.54
H	2.06	2.54
I	1.02	1.27
J	4.83	5.33
K	3.30	3.56
L	2.40	2.66
M	0.46	0.56



Dimensions in millimeters

Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinf